



BOURNS®

Features

- Formerly J. W. Miller® model
- Magnetic shielding
- High Q characteristic
- High current rating
- RoHS compliant*

Applications

- Prevention of electromagnetic interference to signals on the secondary side of electronic equipment

PM1008S Series - Shielded Wirewound Chip Inductors

Electrical Specifications

Bourns Part No.	Inductance μH (@100 KHz)	Tolerance %	Q min. (@ 1 MHz)	SRF MHz min.	DCR Ω max.	I _{dc} mA max.
PM1008S-1R0M-RC	1.0	±20	35	344	0.05	3000
PM1008S-1R5M-RC	1.5	±20	35	260	0.06	2800
PM1008S-1R8M-RC	1.8	±20	35	225	0.09	2000
PM1008S-2R7M-RC	2.7	±20	38	185	0.14	1300
PM1008S-3R9M-RC	3.9	±20	38	175	0.26	1200
PM1008S-4R7M-RC	4.7	±20	38	160	0.35	1000
PM1008S-5R6M-RC	5.6	±20	38	150	0.40	1000
PM1008S-6R8M-RC	6.8	±20	38	120	0.60	850
PM1008S-100M-RC	10	±20	38	105	1.0	780
PM1008S-150M-RC	15	±20	38	35	1.2	700
PM1008S-220M-RC	22	±20	40	26	1.4	650
PM1008S-330M-RC	33	±20	45	20	1.6	500
PM1008S-390M-RC	39	±20	45	16	1.9	450
PM1008S-470M-RC	47	±20	45	14	2.5	400
PM1008S-680M-RC	68	±20	45	12	3.8	300
PM1008S-820M-RC	82	±20	45	9	4.2	280
PM1008S-101M-RC	100	±20	45	7	5.8	260
PM1008S-121M-RC	120	±20	50	6	6.2	250
PM1008S-151M-RC	150	±20	50	5.6	7.5	220
PM1008S-221M-RC	220	±20	55	4.5	10.0	210
PM1008S-331M-RC	330	±20	55	3.8	11.5	200
PM1008S-471M-RC	470	±20	55	3.0	16.5	160
PM1008S-561M-RC	560	±20	55	2.8	18.0	130
PM1008S-681M-RC	680	±20	55	2.5	24.0	120
PM1008S-821M-RC	820	±20	45	1.5	26.0	100
PM1008S-102M-RC	1000	±20	45	1.3	30.0	100

General Specifications

Current Rating
 10 % drop in inductance at I_{dc}
 Temperature Rise
 15 °C max. at rated current
 Operating Temperature
 -40 °C to +85 °C
 Storage Temperature -40 °C to +85 °C
 Reflow Soldering 230 °C; 50 sec max.
 Resistance to Soldering Heat
 260 °C, 5 sec. max.

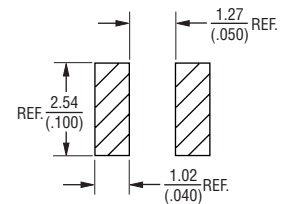
Materials

Core Material Ferrite
 Terminal Electrode Sn/Ni
 Packaging 750 pcs. per reel

Product Dimensions



Recommended Pad Layout



DIMENSIONS: $\frac{\text{MM}}{\text{(INCHES)}}$

*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.
 Specifications are subject to change without notice.
 Customers should verify actual device performance in their specific applications.

